



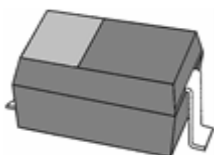
# SEMICONDUCTOR Small Signal Products

## MATERIAL CONTENT LIST

PACKAGE: **SOD-323-G**  
 FAMILY:  
 DATE: July 24, 2020  
 REVISION: 5

**GREEN**  
(5-2008)\*\*

**RoHS**  
COMPLIANT



MATERIAL CONTENT					
Part	Material	CAS N°	weight mg	% of weight	ppm of total weight
<b>Mold compound</b> 61.0%	Silica, Fused	60676-86-0	1.95	79.1%	482504
	Cured polymer (epoxy + phenolic resin reacted)		0.50	20.3%	123719
	Carbon black	1333-86-4	0.02	0.6%	3712
	<b>TOTAL</b>		<b>2.47</b>		
<b>Lead frame</b> 33.0%	Si	7440-21-3	0.004	0.3%	940
	Mn	7439-96-5	0.01	0.7%	2474
	Ni	7440-02-0	0.54	40.5%	133616
	Co	7440-48-4	0.007	0.5%	1608
	Fe	7439-89-6	0.77	57.7%	190527
	Cr	7440-47-3	0.0015	0.1%	371
	C	7440-44-0	0.0003	0.0%	74
	Cu	7440-50-8	0.0015	0.1%	371
<b>TOTAL</b>		<b>1.3336</b>			
<b>L/F plating</b> 0.8%	Ag	7440-22-4	0.033	100.0%	8165
	<b>TOTAL</b>		<b>0.0330</b>		
<b>Terminal finish</b> 2.8%	Sn	7440-31-5	0.114	100.0%	28208
	<b>TOTAL</b>		<b>0.114</b>		
<b>Silicon chip</b>	Si	7440-21-3	0.074	99.6%	18310
	SiO2	14808-60-7	0.0003	0.4%	79
	<b>TOTAL</b>		<b>0.0743</b>		
<b>Chip Metal</b>	Au	7440-57-5	0.0065	100.0%	1608
	And / or traces of As, Ag, Ti, Al, Ni, Pd, Cu				
	<b>TOTAL</b>		<b>0.0065</b>		
<b>Bond wire</b> 0.4%	Au	7440-57-5	0.015	100.0%	3712
	<b>TOTAL</b>		<b>0.015</b>		
<b>Total weight</b>			<b>4.04</b>		

Remarks: Total weight range  $\pm 10\%$   
 Reflow Soldering acc. J-STD-020  
 \* Not detected  
 \*\* Please see document "Vishay Green and Halogen-Free Definitions (5-2008)"  
[http://www.vishay.com/docs/99912/mat\\_cat\\_policy.pdf](http://www.vishay.com/docs/99912/mat_cat_policy.pdf)  
 Material Analysis Reports available on request